GRADUATION THESIS

Analyze and design software to checking weld quality using image processing technology and segmentation deep learning

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ACKNOWLEDGMENTS

I have received a lot of help and support through the work of this thesis.

First, I would like to express my gratitude to my supervisor TS. Trinh Anh Phuclecturer in the School of Information and Communication Technology at the Hanoi University of Science and Technology for his guidance and advice throughout the research.

Second, I would like to acknowledge my colleagues from my internship at ST4I Co., especially my boss, Mr. Pham Anh Duong for giving me the advice and the opportunities to focus on my thesis.

During my 5 years in Hanoi University of Science and Technology, it is impossible not to thank my friends. They have supported me a lot in study, as well as in life. Together we created unforgettable memories in student life.

And finally, I would like to thank my friends and my parents for encouraging and supporting me throughout my study.

ABSTRACT

Locating and identifying printed circuit board (PCB) mounted components based on machine vision is an important and challenging issue for automated PCB inspection and PCB recycling. Through that, we can determine product quality quickly, helping to reduce manpower as well as costs in industrial production. In this project, we propose a depth image-based PCB segmentation method to segment and identify components in a PCB by classification method.

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LIST OF ABBREVIATIONS

| Abriviation | Full Expression |
|-------------|------------------------------|
| AI | Artificial Intelligence |
| AOI | Automated Optical Inspection |
| AUC | Area Under The Curve |
| CNN | Convolutional Neural Network |
| NN | Neural Network |
| MVVM | Model - View - ViewModel |
| SVM | Support Vector Machine |

CHAPTER 1. INTRODUCTION

1.1 Overview

PCB (Printed Circuit Board)(figure 1.1) is a multi-layer and non-conductive printed circuit board in which all the electronic components are connected together on a circuit board and with a base underneath. When there is no PCB, the components are connected by wires, which increases the complexity and the reliability is not high, so it is not possible to create a circuit as large as the motherboard. In a PCB, all the components are connected wirelessly and are wired internally, thus reducing the complexity of the overall circuit design. PCBs are used for power supply and connections between components. PCB can customize any specifications according to user requirements. You can encounter PCB in many electronic devices such as: TV, mobile phone, digital camera, computer parts such as: Graphics card, Motherboard... It is also used in many fields. such as: Medical equipment, industrial machinery, automotive industry, lighting...

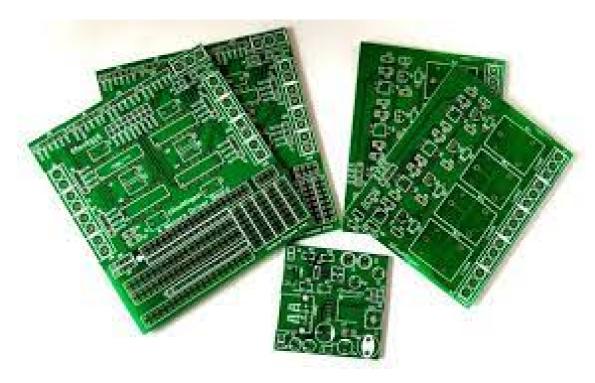


Figure 1.1: Circuit board (PCB) sample

In the electronics industry, error checking on printed circuit boards (PCBs) is an important factor in ensuring product accuracy and safety. Currently, there are many techniques and devices used for error checking on PCBs, including in-circuit testing (ICT), X-ray inspection (figure 1.3), and automated optical inspection (AOI) (figure 1.2). These techniques allow for quick and efficient error detection during